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The lead frame package with dummy chip comprising a lead frame with a plurality of first leads, molding compound, a dummy chip and a die. Wherein the molding compound encapsulates the die and the dummy chip, the dummy chip is arranged on a lower portion of the molding compound. The die is stacked on an upper surface of the dummy chip by using an adhesive material. A plurality of bonding wires are connected between the die and an end of the plurality of leads over the dummy chip.